

SEMI GLOBAL UPDATE

March 31, 2026

What's New at SEMI



Advanced Packaging and Heterogeneous Integration

The Thermal and Power Realities of the AI Era

The future of advanced manufacturing will be defined by how effectively we manage power and heat in heterogeneous systems.



Public Policy and Global Advocacy

SEMI Europe Applauds the European Commission's Implementation Dialogue on the Chips Act 2.0

"With focused execution and unified commitment across institutions and industry, Europe can secure ...," said Laith Altimime, President of SEMI Europe.



Supply Chain Management

Webinar – Co-Intelligence™: The New Architecture of Semiconductor Ecosystems

Discover a new model that connects intelligence across organizations for improved visibility and decision-making in the semiconductor supply chain.



Workforce Development

Solving the Semiconductor Talent Gap by Connecting and Training Talent to Support Industry Needs

Learn more about the first nationally accredited industry-recognized Equipment Maintenance Technician Certification.



SEMI-Related

Semiconductor Engineering: Challenges in Scaling Chips to 2nm And Below

Scaling logic continues to deliver better performance per watt, but it's becoming harder, more expensive, and increasingly customized.

Upcoming Events/Webinars

- | | |
|----------|--|
| Apr 7-8 | Plasma Etching, ALE, & RIE
Virtual Pacific Time |
| Apr 8-10 | Co-Intelligence™: The New Architecture of Semiconductor Ecosystems
Virtual Various Times |
| Apr 13 | Advanced Packaging and Material Characterization for Microelectronics
Virtual GMT +8 |

[More events](#)

More News

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